505396944 03/27/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5443738

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
EIICHI NAKAMOTO	03/04/2019

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	2430014

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16337201

CORRESPONDENCE DATA

Fax Number: (312)803-4960

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: docketing@chiplawgroup.com

CHIP LAW GROUP Correspondent Name: Address Line 1: 155 N WACKER DR

Address Line 2: **SUITE 4250**

Address Line 4: CHICAGO, ILLINOIS 60606

ATTORNEY DOCKET NUMBER:	SP368031US00
NAME OF SUBMITTER:	PRAMOD CHINTALAPOODI
SIGNATURE: /Pramod Chintalapoodi/	
DATE SIGNED:	03/27/2019

Total Attachments: 1

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PATENT REEL: 048721 FRAME: 0067 505396944

Attorney Docket No.: Sony Ref. No.: SP368031US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

As the below named inventor, I hereby declare that: This declaration is directed to: United States application or PCT international application number PCT/JP2017/031532 filed on 2017/09/01 The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at 4-14-1 Asath-cho, Atsigh-shi, Kanagawa, Japan (bereininfer referred to as ASSIGNEE), is desirous of sequiring all interest in, to and under and under and invention, and application disclosure the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all freezing countries. NOW THEREFORE, in consideration of the sum of One Dollar (\$1.60), and other good and voluble consideration, the receipt and sufficiency of which are hereby acknowledged. I by these posents do hereby assign, sell and transfer unto said. ASSIGNEE, its successors, assigns, and legal representatives, the entire relight, lite and interests in additional policients, and application, including any divestors and continuous methods are any and all principle consideration. The patents of the United States, and countries force and interest, which may be granted for said and any and all principles and provides and provides and provides and period provides and pr	Title of Invention	DELTA-SIGMA MODULATOR, ELECTRONIC DEVICE, AND METHOD FOR CONTROLLING DELTA-SIGMA MODULATOR	
The attached application or PCT international application another. PCT/JP2017/031532 filed on 2017/09/01 The above-identified application was made or authorized to be made by me. I believe that I and the original reventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION	As the below	named inventor, I hereby declare that:	
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Inventor: EIICHI NAKAMOTO Date: 2019/3/4	I hereby ackn not more than	owledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of five (5) years, or both.	
	LEGAL NAN	1E OF INVENTOR	
Signature: Etichi Walson oto	Inventor: EIICHI NAKAMOTO Date: 2019/3/4		
	Signature:	Etichi Nalemente	

PATENT REEL: 048721 FRAME: 0068

RECORDED: 03/27/2019